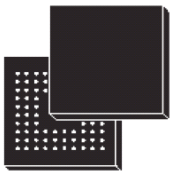
STA538

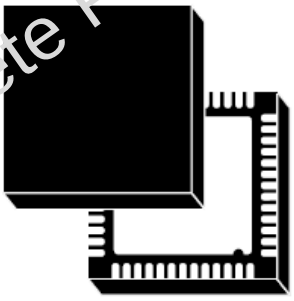
2 x 1.3 W class-D amplifier with analog or digital input 2.0 multichannel digital audio processor with FFX

Features

- Up to 96 dB dynamic range
- Sample rates from 8 kHz to 192 kHz
- FFX™ class-D driver
- 1.5 V to 1.95 V digital power supply
- 1.5 V to 3.6 V analog power supply
- 18-bit audio processing and class-D FFX™ modulator
- Digital volume control:
  - +36 dB to 105 dB in 0.5 dB steps
  - Software volume update
- Individual channel and master gain/attenuation
- Automatic invalid input detect mute
- 2-channel I^2S input/output data interface
- Digitally controlled POP-free operation
- Input and output channel mapping
- 250 mΩ output CMOS R_{dson}
- > 90% efficiency
- 2 x 1.3 W (10% THD) on 4 Ω at 3.6 V
- 2 x 0.7 W (10% THD) on 8 Ω at 3.3 V
- Stereo headphone plus mono speaker application:
  - 50 mW stereo into 32 Ω headphone, 1.2 W mono into 4 Ω speaker at 3.3 V
  - 100 mW stereo into 16 Ω headphone, 1.2 W mono into 4 Ω speaker at 3.3 V



TFBGA48



VFQFPN52

Order codes

Part number	Package
STA538B	TFBGA48 (tube)
STA538Q	VFQFPN52 (tube)

Contents

1 Introduction

The STA538 is a digital stereo class-D audio amplifier. It includes an audio DSP, a ST proprietary high-efficiency class-D driver and CMOS power output stage. It is intended for high-efficiency digital-to-power-audio conversion for portable applications. The STA538 also provides output capabilities for FFX™. In conjunction with a power device, the STA538 provides high-quality digital amplification.

The STA538 contains an on-chip volume/gain control.

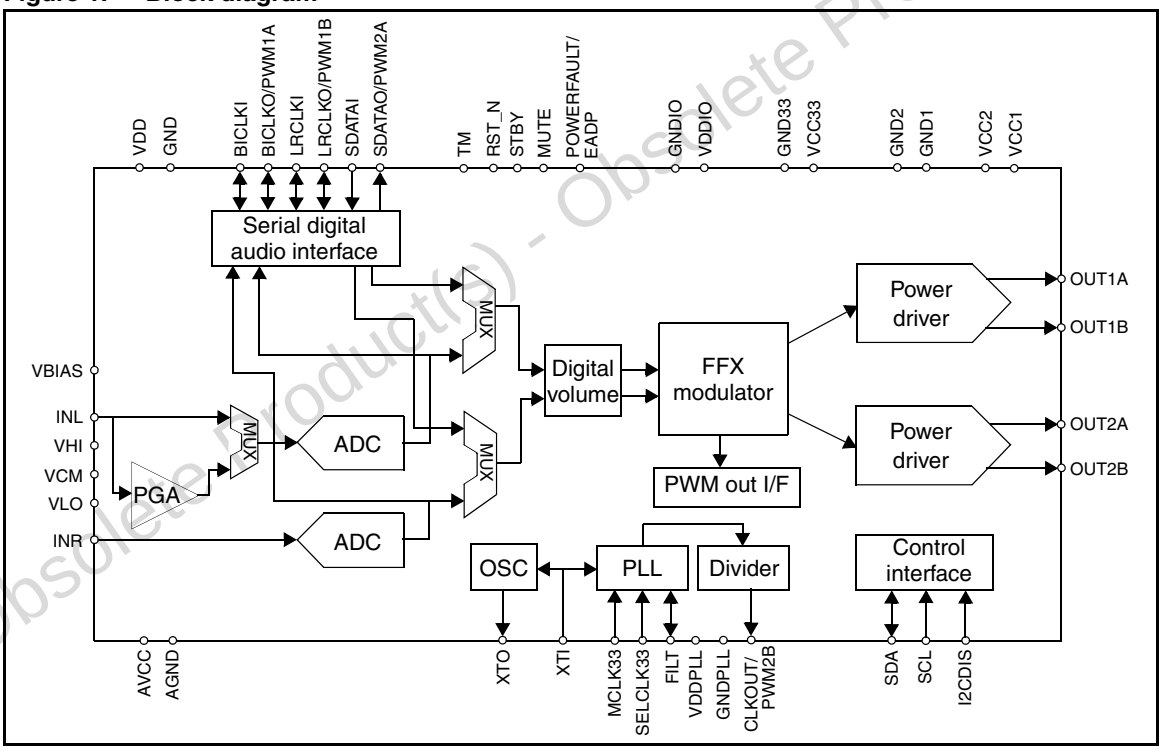
The PWM amplifier achieves greater than 90% efficiency for longer battery life for portable systems.

The innovative class-D modulation, allows the STA538 to work without external LC filters and without a heatsink.

The STA538 I2CDIS pin disables the audio DSP functions to provide a direct conversion of the input signal into output power (the I^2C interface is disabled). This conversion is done without the microcontroller.

The STA538 is designed for low-power operation with extremely low-current consumption in standby mode. It is available in two packages: the TFBGA48 and the VFQFPN52. These are very thin packages (1.2 mm thick) intended for small portable applications.

Figure 1. Block diagram



2 Connection diagrams and pin descriptions

This section includes connection diagrams and pin descriptions for the following packages:

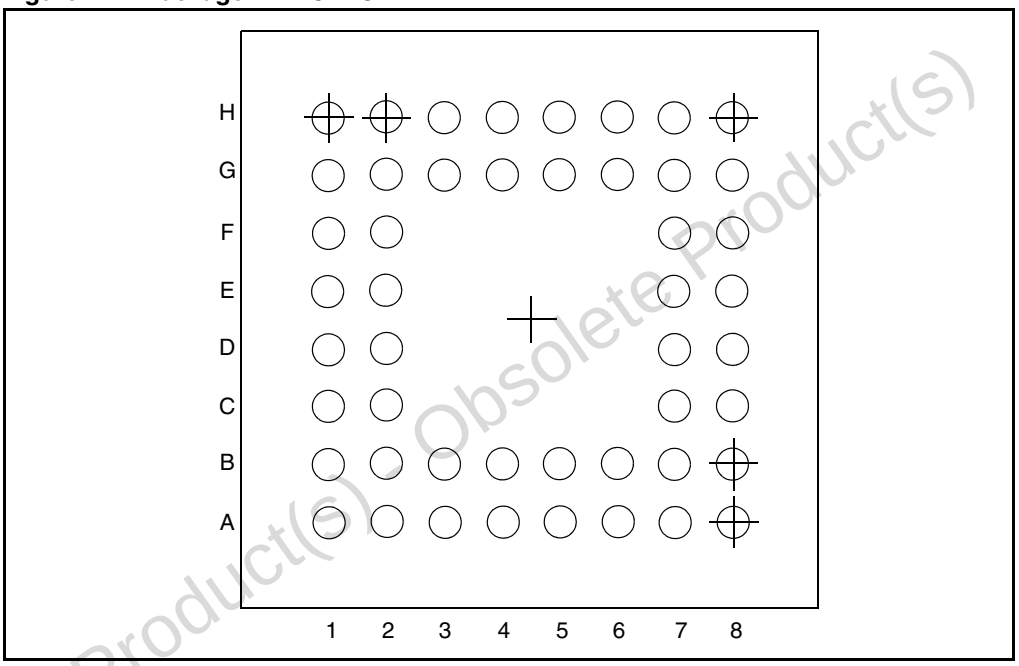
- TFBGA48
- VFQFPN52

2.1 TFBGA48 package

2.1.1 Connection diagram

Figure 2 shows the connection diagram for the TFBGA48 package.

Figure 2. Package: TFBGA48



2.1.2 Pin description

Table 1. Package: TFBGA48

Pin #	Name	Type	Description
D7	RST_N	Digital input	Reset (active low)
D1	XTI	Digital input	Crystal input or master clock input
E1	MCLK33	Digital input	Master clock input 3.3 V capable XTI: crystal input or master clock input 3.3 V capable
G3	SELCLK33	Digital input	Master clock input selector: SELCLK33 = 1 -> MCLK33 selected SELCLK33 = 0 -> XTI selected
D2	XTO	Digital output	Crystal output
C7	CLKOUT/ PWM2B	Digital output	Buffered clock output / PWM2B FFX^{Tm}
F1	SCL	Digital input	I^2C serial clock
G1	SDA	Digital input/output	I^2C serial data
G2	I2CDIS	Digital input	I^2C disable pin (active high)
G8	STBY	Digital input	Standby (active high)
B7	MUTE	Digital input	Mute (active high)
H6	BICLKI	Digital input/output	Input serial audio interface bit-clock
H5	LRCLKI	Digital input/output	Input serial audio interface L/R-clock
E2	SDATAI	Digital input	Input serial audio interface data
G6	BICLKO/ PWM1A	Digital input/output	Output serial audio interface bit-clock (volume DOWN when I2CDIS = 1) / PWM1A FFX^{Tm}
G5	LRCLKO/ PWM1B	Digital input/output	Output serial audio interface L/R-clock (volume UP when I2CDIS = 1) / PWM1B FFX^{Tm}
G4	SDATAO/ PWM2A	Digital output	Output serial audio interface data / PWM2A FFX^{Tm}
H2	TM	Digital input	Test mode (active high)
H7	INL	Analog input	ADC left channel line input or microphone input
H8	INR	Analog input/output	ADC right channel line input
G7	VBIAS	Analog input/output	ADC microphone bias voltage
D8	VCM	Analog input/output	ADC common mode voltage
F8	AVDD	Supply	ADC analog supply
E8	AGND	Ground	ADC analog ground

Table 1. Package: TFBGA48 (continued)

Pin #	Name	Type	Description
F7	VHI	Analog input	ADC high reference voltage
E7	VLO	Analog input	ADC low reference voltage
H1	FILT	Analog input/output	PLL loop filter terminal
H4	VDDPLL	Supply	PLL analog supply
H3	GNDPLL	Ground	PLL analog ground
A6	OUT1A	Analog output	Channel 1 half-bridge A output
B6	OUT1A	Analog output	Channel 1 half-bridge A output
A5	OUT1B	Analog output	Channel 1 half-bridge B output
B5	OUT1B	Analog output	Channel 1 half-bridge B output
A3	OUT2A	Analog output	Channel 2 half-bridge A output
B3	OUT2A	Analog output	Channel 2 half-bridge A output
A4	OUT2B	Analog output	Channel 2 half-bridge B output
B4	OUT2B	Analog output	Channel 2 half-bridge B output
F2	POWERFAULT/ EADP	Digital output	Power fault signal (active high) / external audio power-down signal
A8	VCC1	Supply	Channel 1 power supply
A1	VCC2	Supply	Channel 2 power supply
A7	GND1	Ground	Channel 1 power ground
A2	GND2	Ground	Channel 2 power ground
C2	VCC33	Supply	Pre-driver supply
B2	GND33	Ground	Pre-driver ground
C8	VDD	Supply	Digital supply
B8	GND	Ground	Digital ground
C1	VDDIO	Supply	I/O ring supply
B1	GNDIO	Ground	I/O ring ground

2.1.3 Thermal data

Table 2 gives the thermal resistance specifications for the TFBGA48 and the VFQFPN52.

Table 2. Thermal data

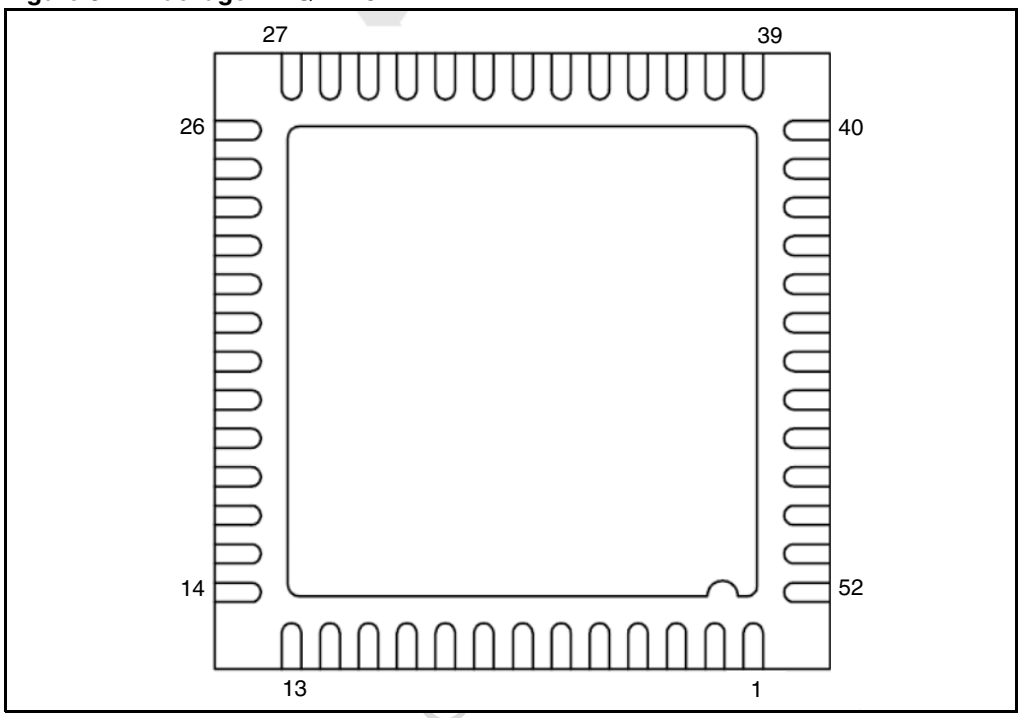
Device	Parameter	Min	Typ	Max	Unit
TFBGA48	Thermal resistance junction to ambient		72		°C/W
VFQFPN52	Thermal resistance junction to ambient		22		°C/W

2.2 VFQFPN52 package

2.2.1 Connection diagram

Figure 3 shows the connection diagram for the VFQFPN52 package.

Figure 3. Package: VFQFPN52



2.2.2 Pin description

Table 3. Package: VFQFPN52

Pin #	Name	Type	Description
10	RST_N	Digital input	Reset (active low)
38	XTI	Digital input	Crystal input or master clock input
37	MCLK33	Digital input	Master clock input 3.3 V capable XTI: crystal input or master clock input 3.3 V capable
36	SELCLK33	Digital input	Master clock input selector: SELCLK33 = 1 -> MCLK33 selected SELCLK33 = 0 -> XTI selected
39	XTO	Digital output	Crystal output
11	CLKOUT	Digital output	Buffered clock output
34	SCL	Digital input	I^2C serial clock
35	SDA	Digital input/output	I^2C serial data
33	I2CDIS	Digital input	I^2C disable pin (active high)
1	STBY	Digital input	Standby (active high)
14	MUTE	Digital input	Mute (active high)
51	BICLKI	Digital input/output	Input serial audio interface bit-clock
47	LRCLKI	Digital input/output	Input serial audio interface L/R-clock
45	SDATAI	Digital input	Input serial audio interface data
52	BICLKO	Digital input/output	Output serial audio interface bit-clock (volume DOWN when I2CDIS=1)
48	LRCLKO	Digital input/output	Output serial audio interface L/R-clock (volume UP when I2CDIS=1)
46	SDATAO	Digital output	Output serial audio interface data
32	TM	Digital input	Test mode (active high)
2	INL	Analog input	ADC left channel line input or microphone input
3	INR	Analog input/output	ADC right channel line input
4	VBIAS	Analog input/output	ADC microphone bias voltage
9	VCM	Analog input/output	ADC Common mode voltage
5	AVDD	Supply	ADC analog supply
8	AGND	Ground	ADC analog ground
6	VHI	Analog input	ADC High reference voltage

Table 3. Package: VFQFPN52 (continued)

Pin #	Name	Type	Description
7	VLO	Analog input	ADC Low reference voltage
40	FILT	Analog input/output	PLL loop filter terminal
42	VDDPLL	Supply	PLL analog supply
41	GNDPLL	Ground	PLL analog ground
16	OUT1A	Analog output	Channel 1 half-bridge A output
19	OUT1B	Analog output	Channel 1 half-bridge B output
25	OUT2A	Analog output	Channel 2 half-bridge A output
22	OUT2B	Analog output	Channel 2 half-bridge B output
31	POWERFAULT/ EADP	Digital output	Power fault signal (active high)/external audio power down signal
15	VCC1A	Supply	Channel 1 half-bridge A power supply
20	VCC1B	Supply	Channel 1 half-bridge B power supply
26	VCC2A	Supply	Channel 2 half-bridge A power supply
21	VCC2B	Supply	Channel 2 half-bridge B power supply
17	GND1A	Ground	Channel 1 half-bridge A power ground
18	GND1B	Ground	Channel 1 half-bridge B power ground
24	GND2A	Ground	Channel 2 half-bridge A power ground
23	GND2B	Ground	Channel 2 half-bridge B power ground
30	VCC33	Supply	Pre-driver supply
27	GND33	Ground	Pre-driver ground
13	VDD1	Supply	Digital supply
12	GND1	Ground	Digital ground
44	VDD2	Supply	Digital supply
43	GND2	Ground	Digital ground
29	VDDIO1	Supply	I/O ring supply
28	GNDIO1	Ground	I/O ring ground
50	VDDIO2	Supply	I/O ring supply
49	GNDIO2	Ground	I/O ring ground

3 Electrical specifications

This section includes the electrical specifications for the STA538.

3.1 Maximum and recommended operating conditions

Table 4 provides the maximum ratings and *Table 5* the recommended operating conditions.

Table 4. Absolute maximum ratings

Signal	Description	Min	Max	Unit
VDD/VDD1/VDD2	Digital supply voltage	-0.5	+2.5	V
AVDD	ADC supply voltage	-0.5	+4	V
VDDPLL	PLL analog supply voltage	-0.5	+2.5	V
VCC1A/1B/2A/2B	Power stage supply voltage	-0.5	+4	V
VCC33	Pre-driver supply	-0.5	+4	V
VDDIO	Digital I/O supply	-0.5	+4	V
V_{DI}	Voltage range digital in	-0.5	VDDIO +0.3	V
V_{AI}	Voltage range analog in	-0.5	AVDD +0.3	V
V_o	Voltage on output pins	-0.5	VDDIO +0.3	V
T_{STG}	Storage temperature	-40	150	°C
T_{AMB}	Ambient operating temperature	-20	85	°C

Note: All grounds must be within 0.3 V of each other.

Table 5. Recommended operating conditions

Symbol	Parameter	Min	Typ	Max	Unit
VDD/VDD1/VDD2	Digital supply voltage	1.55	1.8	1.95	V
AVDD	ADC supply voltage	1.8	3.3	3.6	V
VDDPLL	PLL analog supply voltage	1.55	1.8	1.95	V
VCC1A/1B/2A/2B	Power stage supply voltage	1.8	3.3	3.6	V
VCC33	Pre-driver supply	1.8	3.3	3.6	V
GND1, GND2, GND33	Channel 1 and 2 power ground, pre-driver ground		0		
T_{AMB}	Ambient operating temperature	0	25	70	°C

3.2 Electrical characteristics

Table 6 lists the device's electrical characteristics (see also *Table 5* for supply voltages).

Table 6. Electrical characteristics

Symbol	Parameter	Test conditions	Min	Typ	Max	Unit
Eff	Output power efficiency			90		%
R_{dson}	Output stage N/PMOS on-resistance			250		mΩ
IstbyL	Logic power supply current at standby			1.3		µA
IstbyP	Bridges power supply current in standby			0.7		µA
IddL	Logic power supply current at operating			15		mA
IddP	Bridges power supply current at operating			0.5		mA
Tds	Low current dead time (static)			1		ns
Tdd	High current dead time (dynamic)			2.5		ns
Tr	Rise time			3		ns
Tf	Fall time			3		ns
DNR	Dynamic range A-weighted	Speaker mode		96		dB
SNR	Signal-to-noise ratio (A-weighted)	Speaker mode		92		dB
THDN	Total harmonic distortion	0 dBFS input, 8 Ω load speaker		0.1		%
THDN	Total harmonic distortion	-6 dBFS input, 8 Ω load speaker		0.05		%
THDN	Total harmonic distortion	0 dBFS input, 32 Ω load headphone		0.1		%
THDN	Total harmonic distortion	-6 dBFS input, 32 Ω load headphone		0.05		%

Note: LRCLKI frequency (Fs) = 48 kHz, input frequency = 1 kHz, and R_{load} = 32 Ω unless otherwise specified.

The following tables give the distortion values for headphones and speakers.

Table 7. Load power at 1% distortion headphone mode

Load (Ω)	P (mW) at 1.8 V	P (mW) at 3.3 V	P (mW) at 3.6 V
16	20	70	80
32	10	32	40

Table 8. Load power at 1% distortion speaker mode

Load (Ω)	P (mW) at 1.8 V	P (mW) at 3.3 V	P (mW) at 3.6 V
4	240	860	1000
8	150	530	630
16	90	300	350
32	50	165	195

Table 9. Load power at 10% distortion speaker mode

Load (Ω)	P (mW) at 1.8 V	P (mW) at 3.3 V	P (mW) at 3.6 V
4	300	1100	1300
8	195	677	812
16	110	380	450
32	61	210	250

3.3 Lock time

Table 10 gives the typical lock time of the PLL using the suggested loop filter, 1.8 V supply voltage and 30 °C junction temperature.

Table 10. PLL lock time

Parameter	Value
Lock time	200 µs

3.4 ADC performance values

Table 11. Programmable gain performance

Parameter	Min	Typ	Max	Unit
Dynamic range 1 kHz 3.3 V supply				dB
Dynamic range 1 kHz 1.8 V supply				dB
Dynamic range 1 kHz 3.3 V supply A-weighted		92		dB
Dynamic range 1 kHz 1.8 V supply A-weighted		84		dB
SNDR 1 kHz 3.3 V supply				dB
SNDR 1 kHz 1.8 V supply				dB
SNDR 1 kHz 3.3 V supply A-weighted		92		dB
SNDR 1 kHz 1.8 V supply A-weighted		84		dB
THD 1 kHz (-1 dB input) 1.8 V supply		75		dB
THD 1 kHz (-1 dB input) 3.3 V supply		85		dB
Deviation from linear phase				degree
Pass band				kHz
Pass band ripple				dB
Stop band				kHz
Stop band attenuation				dB
Group delay 8 kHz				ms
Group delay 48 kHz				ms
Cross talk 1.8 V				dB
Cross talk 3.3 V				dB

4 Digital processing

The STA538 processor block is a digital block providing two channels of audio processing and channel-mapping capability.

4.1 Signal processing flow

I^2S or stereo ADC data can be selected. The I^2S frequency range is from 8 kHz to 192 kHz. ADC sampling frequency can be selected from 8 kHz to 48 kHz.

4.2 I^2C interface disabled

When pin I2CDIS = 1, the SDA, SCL, LRCLKO and BICLKO pins can be pulled high or low to change certain parameters of operation.

- SDA = 0: FFX input comes from ADC
  SDA = 1: FFX input comes from digital audio interface
- SCL = 0: binary output mode (binary soft start/stop enabled)
  SCL = 1: phase shift output mode
- LRCLKO = 0: no volume change
  LRCLKO = 1: volume up
- BICLKO = 0: no volume change
  BICLKO = 1: volume down

At power up, the master volume is set to -60 dB. When holding pin LRCLKO = 1 and pin BICLKO = 1 simultaneously, the master volume is set to 0 dB. A high pulse on pin LRCLKO causes a master volume change of +0.5 dB and a high pulse on pin BICLKO causes a master volume change of -0.5 dB.

4.3 Volume control and gain

The volume control structure of the STA538 consists of individual volume registers for each channel and a master volume register that provides an offset to each channel's volume setting. The individual channel volumes are adjustable in 0.5 dB steps from +36 dB to -91.5 dB. As an example, if register LVOL = 0x00 or +36 dB and register MVOL = 0x18 or -12 dB, then the total gain for the left channel is +24 dB.

When the mute bit is set to 1, all channels are muted. The volume control provides a soft mute with the volume ramping down to mute in 4096 samples from the maximum volume setting at the internal processing rate (~48 kHz).

Table 12. Master volume offset as a function of register MVOL

MVOL[7:0]	Volume offset from channel value
0x00	0 dB
0x01	-0.5 dB
0x02	-1dB
…	…
0x78	-60 dB
…	…
0xFE	-105 dB
0xFF	Hard master mute

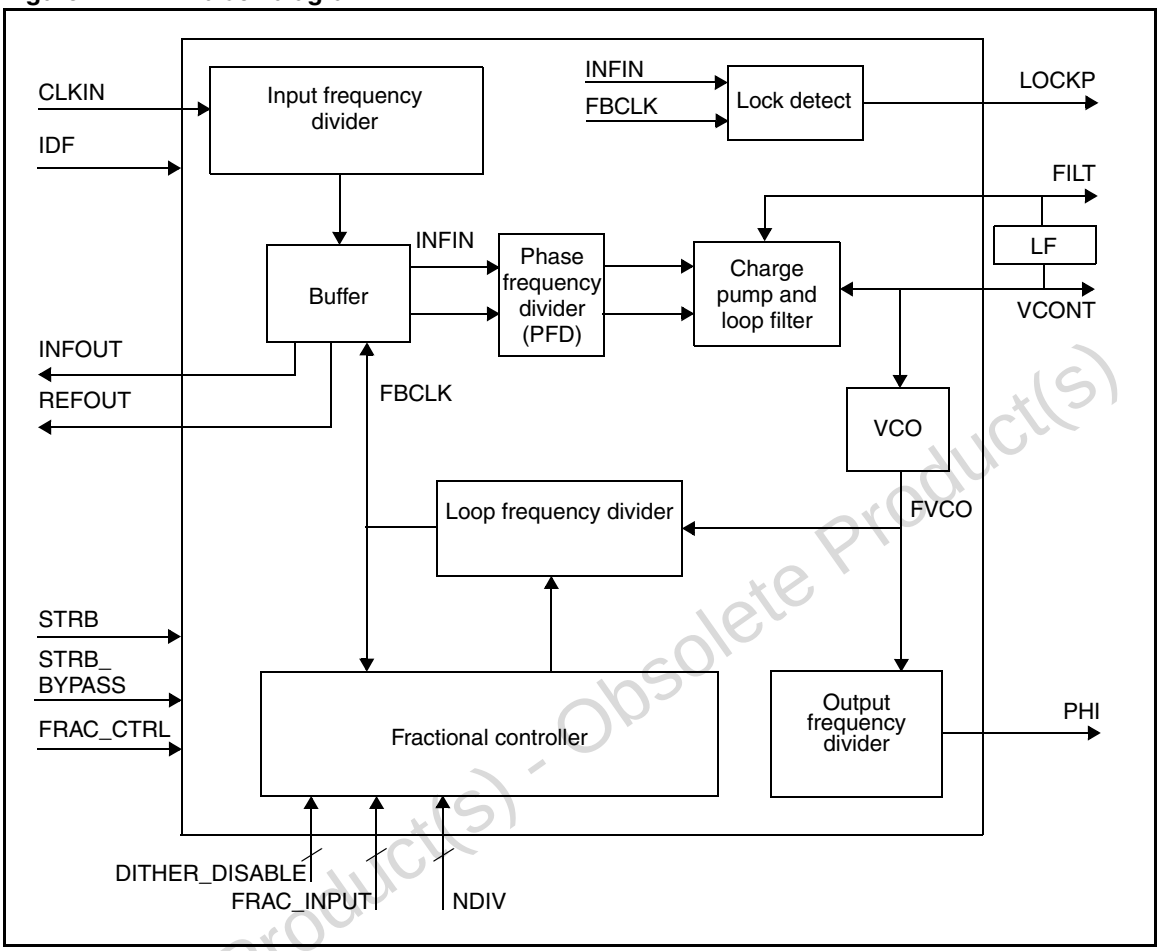
Table 13. Channel volume as a function of registers LVOL and RVOL

LVOL/RVOL[7:0]	Volume
0x00	+36 dB
0x01	+35.5 dB
0x02	+35 dB
…	…
0x47	+0.5 dB
0x48	0 dB
0x49	-0.5 dB
…	…
…	…
0xFF	-91.5 dB

5 PLL

Figure 4 shows the main components of the PLL.

Figure 4. PLL block diagram



5.1 Functional description

Phase/frequency detector

The phase/frequency detector (PFD) compares the phase difference between the corresponding rising edges of INFIN and FBCLK, (clock output from the loop frequency divider) by generating voltage pulses with widths proportional to the input phase error.

Charge pump and loop filter

This block converts the voltage pulses from the phase/frequency detector to current pulses which charge the loop filter and generate the control voltage for the voltage-controlled oscillator. The loop filter is placed external to the PLL on pin FILT.

Voltage controlled oscillator

The voltage controlled oscillator (VCO) is the oscillator inside the PLL. It produces a frequency output (FVCO) proportional to the input control voltage.

Input frequency divider

This frequency divider divides the PLL input clock CLKIN by a factor called the input division factor (IDF) to generate the PFD input frequency INFIN.

Loop frequency divider

This frequency divider is present within the PLL for dividing FVCO by a factor called the loop division factor (LDF). The output of this block is the FBCLK.

Output frequency divider

The PLL output PHI is generated by dividing the FVCO by the output division factor (ODF). The divider that divides the FVCO to generate the clock to the core is called the output frequency divider. In the STA538, the ODF is fixed to be divisible by 2 and cannot be configured.

Lock-detect circuit

The output of this block (the LOCKP signal) is asserted high when the PLL enters the state of COARSE LOCK in which the output frequency is within +/-10% (approximately) of the desired frequency. The LOCKP signal is refreshed every 32 cycles of the INFIN. The generated value is based on the result of comparing the number of FBCLK cycles in a window of 14 INFIN cycles. The different cases generated after comparison are as follows.

- If LOCKP is already at 0, then in the next refresh cycle LOCKP goes to 1 if the number of FBCLK cycles in the 14-cycle INFIN window is 13, 14, or 15. Otherwise LOCKP stays at 0.
- If LOCKP is already at 1, then in the next refresh cycle LOCKP goes to 0 if the number of FBCLK cycles in the 25-cycle INFIN window is less than 11 or higher than 17, otherwise LOCKP stays at 1.
- If LOCKP is already at 1 and CLKIN is lost (no longer present on the input pin), LOCKP stays at 1. In this case, the PLL is unlocked.

PLL filter

Figure 5 shows the PLL filter scheme. Recommended values are R1 = 12.5 kΩ, C1 = 250 pF, and C2 = 82 pF.

Figure 5. PLL filter scheme

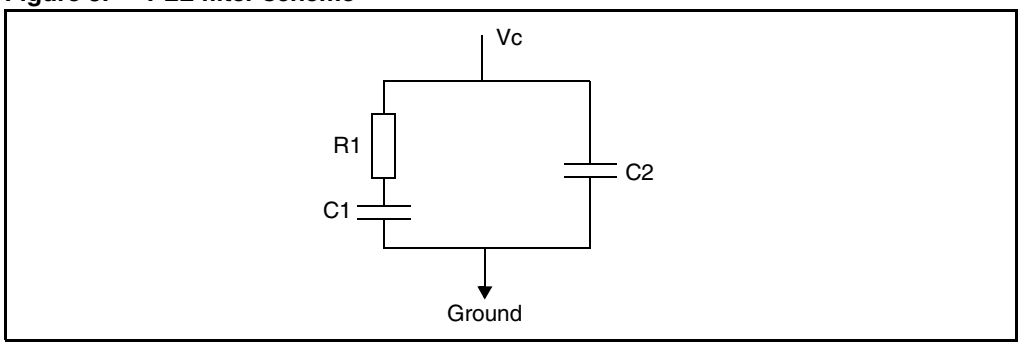


Table 10 on page 14 gives a typical lock time value for the PLL.

5.2 Configuration examples

The STA538 PLL can be configured in two ways:

- default startup configuration
- direct PLL programming

The default startup configuration reads the device's defaults. With this configuration, it is not necessary to program the PLL dividers directly as some presets are used. In this mode, the oversampling ratio between pins XTI (or MCLK33) and LRCLKI is fixed to 256.

The direct PLL programming bypasses the automatic presets allowing direct programming of the PLL dividers.

The output PLL frequency can be determined as following:

Output division factor:

$ODF = 2$

Relation between input and output clock frequency:

$F_{INFIN} = F_{XTI} / IDF$

If register bit PLLCFG0.FRAC_CTRL = 1

$F_{VCO} = F_{INFIN} * (LDF + FRACT/2^{16} + 1/2^{17})$

$F_{PHI} = F_{VCO} / ODF$

When register bit PLLCFG0.DITHER_DISABLE[1] = 1, the $1/2^{17}$ factor is not in the multiplication. This is recommended in order to keep register bit PLLCFG0.DITHER_DISABLE[1] = 0, otherwise there can be spurious signals in the output clock spectrum.

If register bit PLLCFG0.FRAC_CTRL = 0, then:

$F_{VCO} = F_{INFIN} * LDF$

$F_{PHI} = F_{VCO} / ODF$

In the above equations:

FRACT = Decimal equivalent of register bit PLLCFG1.FRAC_INPUT[15:0]

IDF = Input division factor (refer to previous formulas)

LDF = Loop division factor (refer to previous formulas)

ODF = Output division factor = 2

F_{INFIN} = INFIN frequency

F_{XTI} = XTI frequency

F_{VCO} = VCO frequency

F_{PHI} = Frequency of the PLL output clock

When selecting the value of IDF, LDF and FRACT make sure the following limits are maintained:

$2.048\ MHz < F_{XTI} < 49.152\ MHz$

$2.048\ MHz < F_{INFIN} < 16.384\ MHz$

$65.536\ MHz < F_{VCO} < 98.304\ MHz$

There are also some additional constraints on IDF and LDF. IDF should be greater than 0, LDF should be greater than 5 if FRAC_CTRL = 0 and greater than 8 if FRAC_CTRL = 1.

When automatic settings are not used, the PLL must be configured to generate an internal frequency of N * Fs, where Fs is the LRCLKI pin frequency. Values of N are given in *Table 14*.

Table 14. Oversampling table

Fs (kHz)	N	F_{PHI} (MHz)
8	4096	32.768
11.025	4096	45.1584
12	4096	49.152
16	2048	32.768
22.05	2048	45.1584
24	2048	49.152
32	1024	32.768
44.1	1024	45.1584
48	1024	49.152
64	512	32.768
88.2	512	45.1584
96	512	49.152
128	256	32.768
176.4	256	45.1584
192	256	49.152

Example 1:

F_{XTI} = 13 MHz
Fs = 44.1 kHz

IDF should be equal to 3 otherwise LDF become less than 8 (FRAC_CTRL must be 1):

LDF = floor(45.1584/(13/IDF)) = 10

FRACT = round([(45.1584/(13/ IDF))-floor(45.1584/(13/ IDF))]*2^{16}) = 27602

(where:
floor: rounded towards zero
round: rounded real number to nearest integer)

Using the above configuration, the system clock is 45.15841675 MHz, the approximate static error is 16 Hz (that is, 0.5 ppm).

Example 2:

F_{XTI} = 19.2 MHz
Fs = 48 kHz

IDF should be equal to 4 otherwise LDF become less than 8 (FRAC_CTRL must be 1):

LDF = floor(49.152/(19.2/IDF)) = 10

FRACT = round([(49.152/(19.2/IDF))-floor(49.152/(19.2/IDF))]*2^{16}) = 15728

Using the above configuration, the system clock is 49.151953125 MHz, the approximate static error is 47 Hz (that is, 1 ppm).

6 ADC

This section describes the analog-to-digital converter (ADC).

6.1 Functional description

The STA538 analog input is provided through a low power, low voltage, stereo audio analog-to-digital converter front-end designed for audio applications. It includes a programmable gain amplifier, anti-aliasing filter, low-noise microphone biasing circuit, a third-order MASH2-1 delta-sigma modulator, digital decimating filter, and a first-order DC-removal filter. This device is fabricated using a 0.18 µm CMOS process, where high-speed precision analog circuits are combined with high-density logic circuits.

The ADC works in a microphone input (mic-in) mode and in a line-input mode.

If the line input mode is selected, the ADC is configured in stereo and all conversion channels are active.

If the microphone input mode is selected, the ADC is configured in mono. The mono channel is routed through the left conversion path, and the right conversion path is kept in power-down mode to minimize power consumption. A programmable gain amplifier (PGA) is available in mic-in mode, giving the possibility to amplify the signal from 0 to +42 dB in steps of 6 dB.

6.1.1 Digital filter characteristics

The digital filter characteristics are shown in *Table 15*.

Table 15. Digital filter characteristics

Parameter	Typical	Unit
Passband	0.4535 * Fs	kHz
Passband ripple:		
Fs mode	0.08 at 44.1 kHz	dB
Fs_by_2 mode	0.08 at 22.05 kHz	dB
Fs_by_4 mode	0.08 at 11.025 kHz	dB
Stop band attenuation:		
Fs mode	45 at 44.1 kHz	dB
Fs_by_2 mode	45 at 22.05 kHz	dB
Fs_by_4 mode	45 at 11.025 kHz	dB
Group delay:		
Fs mode	0.4 at 32 kHz	ms
Fs_by_2 mode	0.7 at 16 kHz	ms
Fs_by_4 mode	1.4 at 8 kHz	ms

6.1.2 High-pass filter characteristics

Table 16. High-pass filter characteristics

Parameter	Typical	Unit
Frequency response: -3 dB -0.08 dB	 7 50	 Hz Hz
Phase deviation at 20 Hz	19.35	degree
Passband ripple	0.08	dB

6.1.3 Programmable gain amplifier

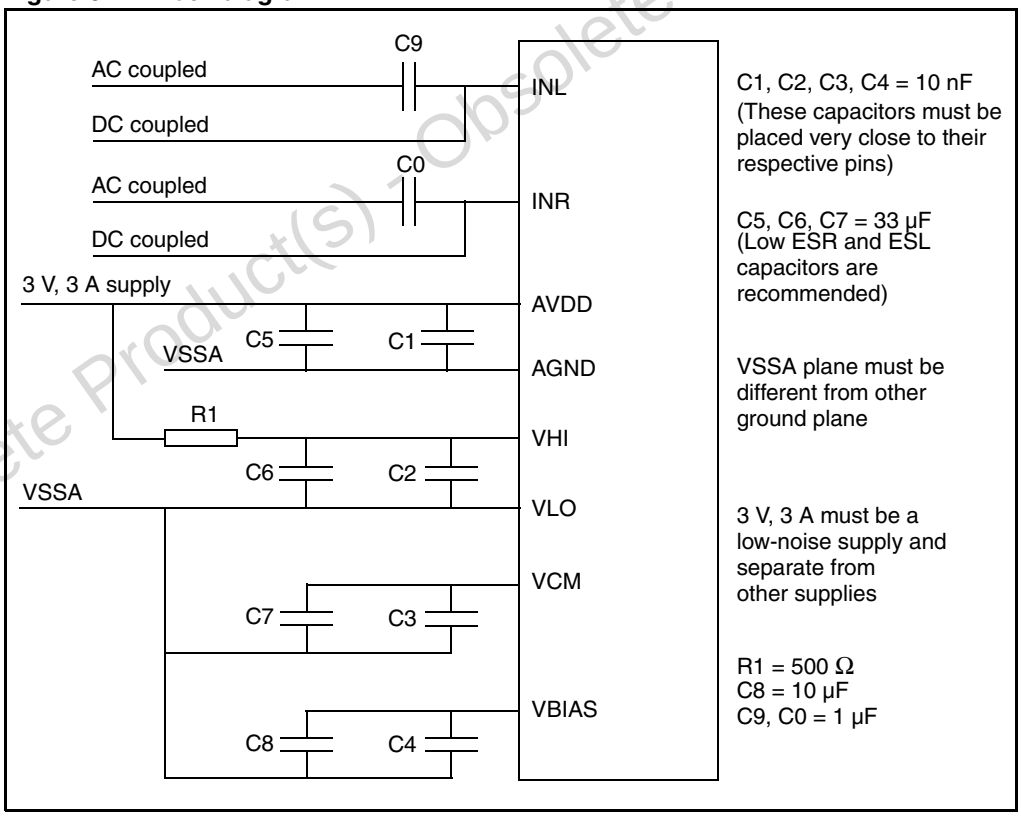
The programmable gain amplifier (PGA) is available in mic-in mode only. It is possible to amplify the input signal from 0 to 42 db in steps of 6 db. The setting is done through PGA bits of the ADCCFG register (see *ADCCFG on page 50* for details).

See *Table 11 on page 15* for performance values.

6.2 Application scheme

Figure 6 shows the filter circuit.

Figure 6. Block diagram



6.3 Configuration examples

The ADC sampling frequency can be selected from three values:

- normal (from 32 kHz to 48 kHz)
- low (from 16 kHz to 24 kHz)
- very-low (from 8 kHz to 12 kHz)

The setting is done through register bits MISC.ADC_FS_RANGE (see *MISC on page 51* for details). For all other settings, register ADCCFG is used (see *ADCCFG on page 50* for details).

7 Driver configuration

A driver configuration is available that allows PWM commands to be used on an external power device. For this purpose, the output serial audio interface is disabled and the respective pins have an alternative name and new functionality, as shown in *Table 17*.

Table 17. Pin functionality in driver-configuration mode

Pin	Alternative pin name and functionality
BICLKO	PWM1A (external bridge PWM command for output 1A)
LRCLKO	PWM1B (external bridge PWM command for output 1B)
SDATAO	PWM2A (external bridge PWM command for output 2A)
CLKOUT	PWM2B (external bridge PWM command for output 2B)
POWERFAULT	EADP (external audio power-down signal)

The driver configuration is selected with two programmable registers PWMINT1 = 0x93 and PWMINT2 = 0x81 (see *PWMINT1* and *PWMINT2 on page 52*).

7.1 I^2S bypass

A configuration is available which allows the bypassing of the I^2S input signal straight to the I^2S output signal.

This configuration is set using two programmable registers PWMINT1 = 0x93 and PWMINT2 = 0x80 (see *PWMINT1* and *PWMINT2 on page 52*).

8 Serial audio interface

This section includes information about the audio interface.

8.1 Specifications

The serial-to-parallel interface and the parallel-to-serial interface can have different sampling rates.

The following terms are used in this section:

- **BICLK active edge:** Pins SDATAI, SDATAO, LRCLKI, LRCLKO always change synchronously with BITCLK active edges. The active edge can be configured to a rising or falling edge via register programming.
- **BICLK strobe edge:** Pins SDATAI, SDATAO, LRCLKI, LRCLKO should be stable near BICLK strobe edges, the slave device is able to use strobe edges to latch serial data internally.

8.2 Master mode

In this mode, pins BICLKI/BICLKO and pins LRCLKI/LRCLKO are configured as outputs.

Figure 7. Master mode

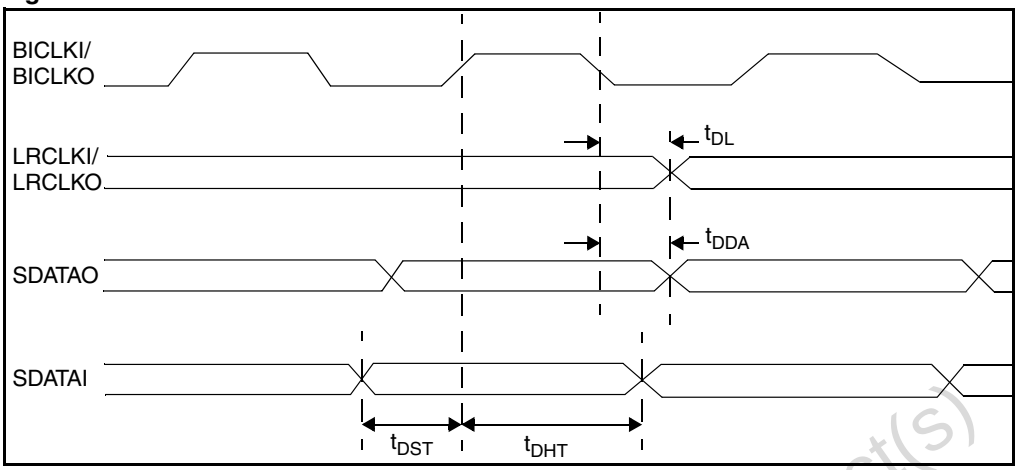


Table 18. Master mode

Parameter	Symbol	Min	Typ	Max	Unit
LRCLKI/LRCLKO propagation delay from BICLK active edge	t_{DL}	0		10	ns
SDATAI propagation delay from BICLKI/O active edge	t_{DDA}	0		15	ns
Sdatao setup time to BICLKI/O strobing edge	t_{DST}	10			ns
Sdatao hold time from BICLKI/O strobing edge	t_{DHT}	10			ns

8.3 Slave mode

In this mode, pins BICLKI/O and pins LRCLKI/O are configured as inputs.

Figure 8. Slave mode

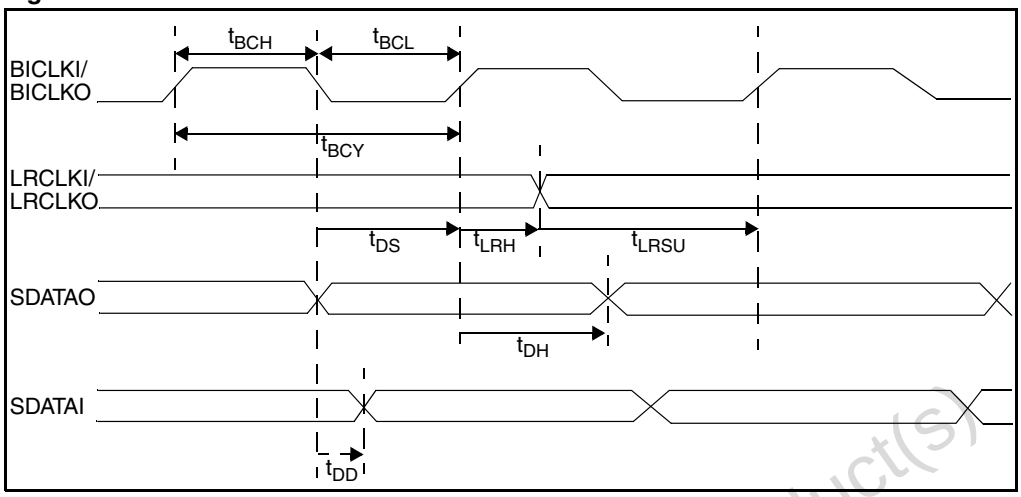


Table 19. Slave mode

Parameter	Symbol	Min	Typ	Max	Unit
BICLK cycle time	t_{BCY}	50			ns
BICLK pulse width high	t_{BCH}	20			ns
BICLK pulse width low	t_{BCL}	20			ns
LRCLKI/LRCLKO setup time to BICLK strobing edge	t_{LRSU}	10			ns
LRCLKI/LRCLKO hold time to BICLK strobing edge	t_{LRH}	10			ns
SDATAO setup time to BICLK strobing edge	t_{DS}	10			ns
SDATAO hold time to BICLK strobing edge	t_{DH}	10			ns
SDATAI propagation delay from BICLK active edge	t_{DD}	0		10	ns

8.4 Serial formats

Different audio formats are supported in both master and slave modes. Clock and data configurations can be customized to match most of the serial audio protocols available on the market.

Data length can be customized for 8-, 16-, 24-, and 32-bit.

Figure 9. Right justified

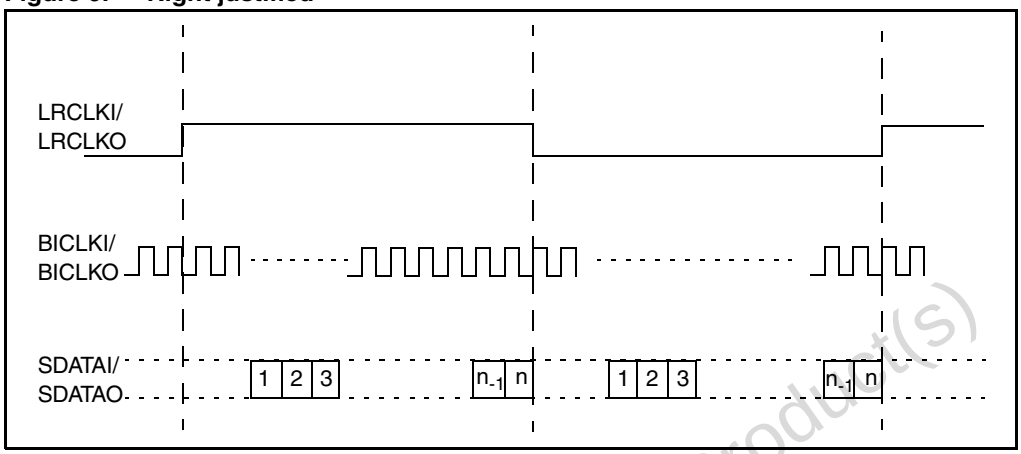
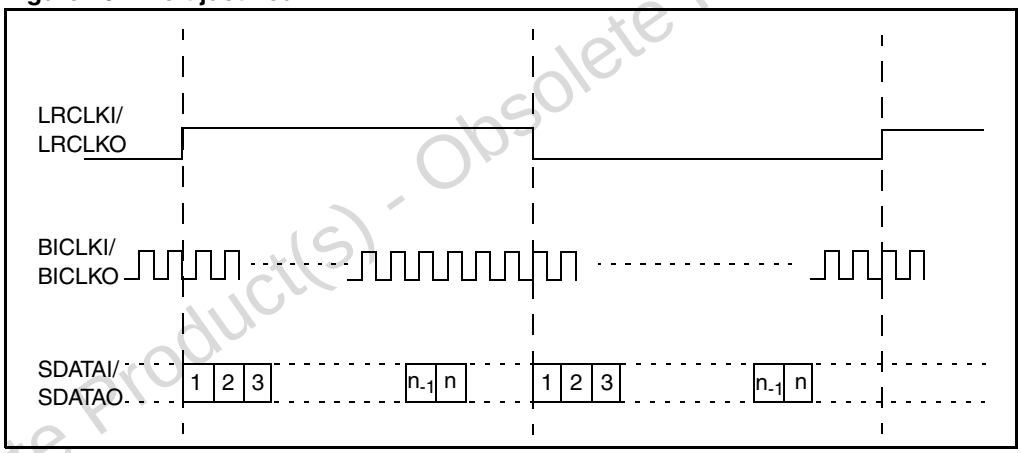
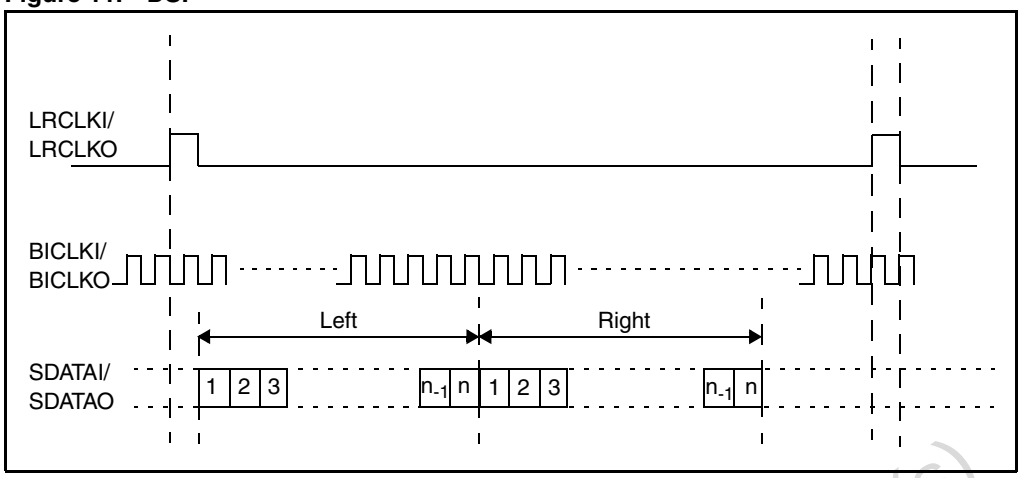


Figure 10. Left justified



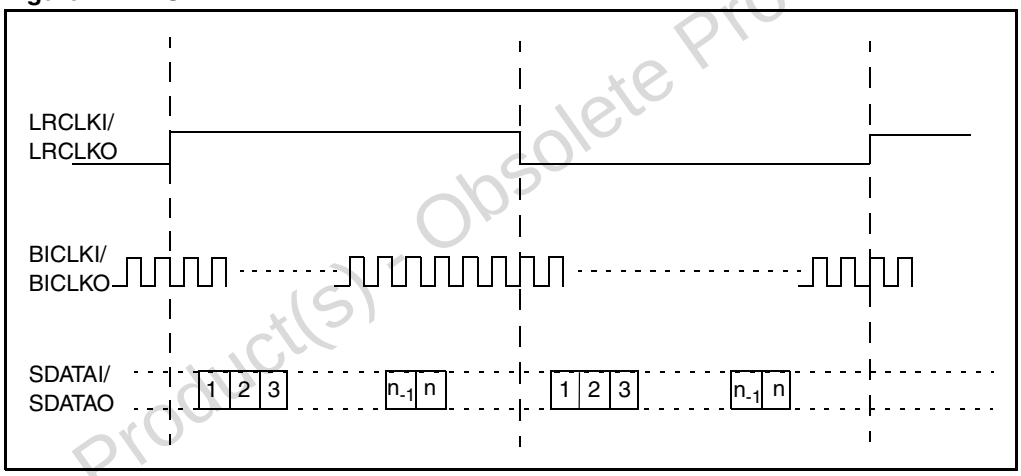
8.4.1 DSP

Figure 11. DSP



8.4.2 I^2S

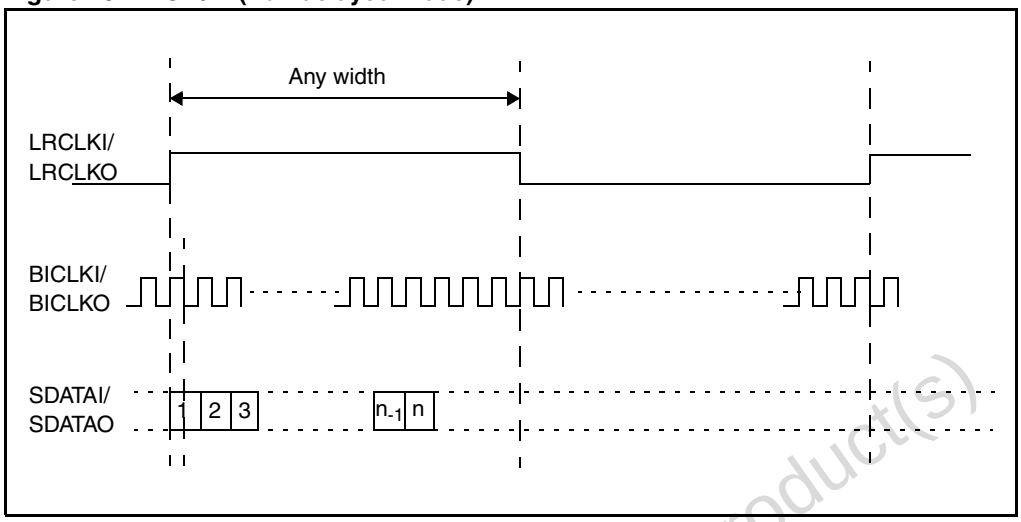
Figure 12. I^2S



8.4.3 PCM/IF (non-delayed mode)

- MSB first
- 16-bit data

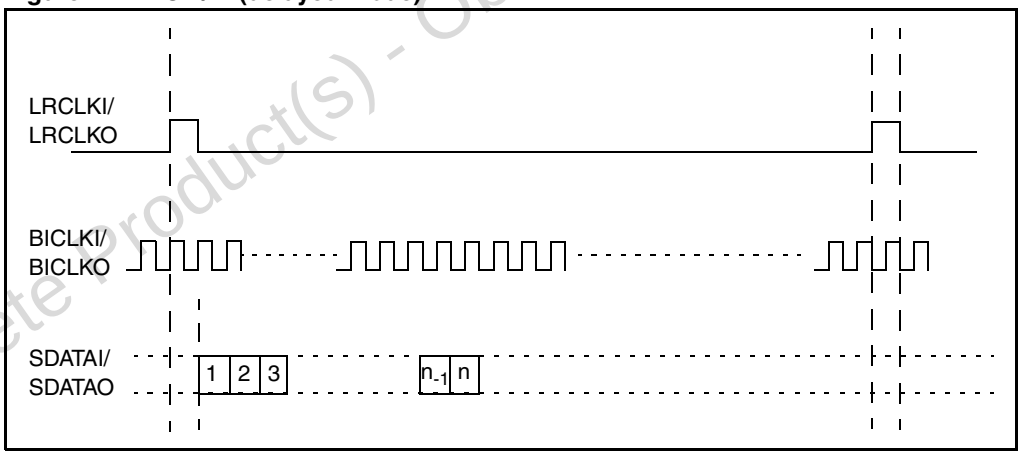
Figure 13. PCM/IF (non delayed mode)



8.4.4 PCM/IF (delayed mode)

- MSB first
- 16-bit data

Figure 14. PCM/IF (delayed mode)



9 I²C interface

This section describes the communication protocol of the I²C interface.

9.1 Data transition and change

Data changes on the SDA line must only occur when the SCL clock is low. SDA transition while the clock is high is used to identify a start or stop condition.

9.2 Start condition

A start condition is identified by a high to low transition of the data bus SDA signal while the clock signal SCL is stable in the high state. A start condition must precede any command for data transfer.

9.3 Stop condition

A stop condition is identified by low to high transition of the data bus SDA signal while the clock signal SCL is stable in the high state. A stop condition terminates communication between the STA538 and the master bus.

9.4 Data input

During data input, the STA538 samples the SDA signal on the rising edge of clock SCL. For correct device operation the SDA signal must be stable during the rising edge of the clock and the data can change only when the SCL line is low.

9.5 Device addressing

To start communication between the master and the STA538, the master must initiate with a start condition. Following this, the master sends onto the SDA line 8 bits (MSB first) corresponding to the device select address and read or write mode.

The 7 most significant bits are the device address identifiers, corresponding to the I²C bus definition. In the STA538, the I²C interface has the device address 0x34.

The 8th bit (LSB) identifies read or write operation (R/W), this bit is set to 1 in read mode and 0 in write mode. After a start condition, the STA538 identifies on the bus the device address and if a match is found, it acknowledges the identification on SDA bus during the 9th bit time. The byte following the device identification byte is the internal space address.

9.6 Write operation

Following the start condition the master sends a device select code with the R/W bit set to 0. The STA538 acknowledges this and the writes to the byte of the internal address. After receiving the internal byte address, the STA538 responds with an acknowledgement.

9.6.1 Byte write

In the byte-write mode the master sends one data byte. This is acknowledged by the STA538. The master then terminates the transfer by generating a stop condition.

9.6.2 Multi-byte write

The multi-byte write modes can start from any internal address. The master generates a stop condition which terminates the transfer.

9.7 Read operation

9.7.1 Current address byte read

Following the start condition the master sends a device select code with the R/W bit set to 1. The STA538 acknowledges this and then responds by sending one byte of data. The master then terminates the transfer by generating a stop condition.

9.7.2 Current address multi-byte read

The multi-byte read modes can start from any internal address. Sequential data bytes are read from sequential addresses within the STA538. The master acknowledges each data byte read and then generates a stop condition terminating the transfer.

9.7.3 Random address byte read

Following the start condition the master sends a device select code with the R/W bit set to 0. The STA538 acknowledges this and then the master writes the internal address byte. After receiving the internal byte address, the STA538 again responds with an acknowledgement. The master then initiates another start condition and sends the device select code with the R/W bit set to 1. The STA538 acknowledges this and then responds by sending one byte of data. The master then terminates the transfer by generating a stop condition.

9.7.4 Random address multi-byte read

The multi-byte read modes could start from any internal address. Sequential data bytes are read from sequential addresses within the STA538. The master acknowledges each data byte read and then generates a stop condition terminating the transfer.

Figure 15. I²C write operations

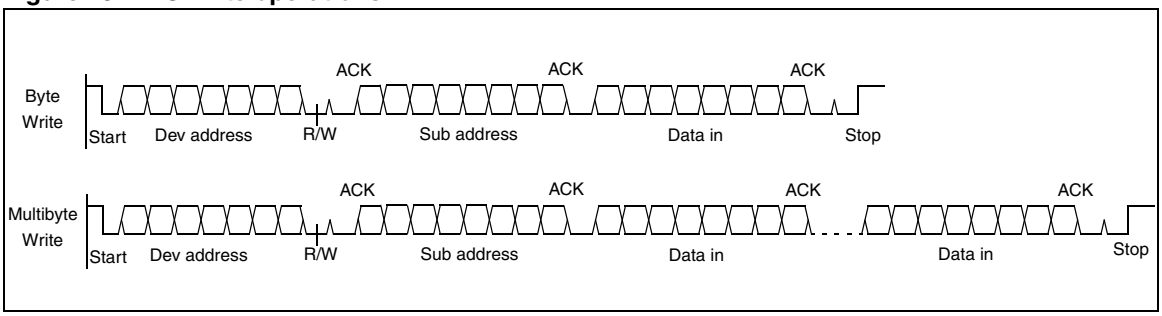
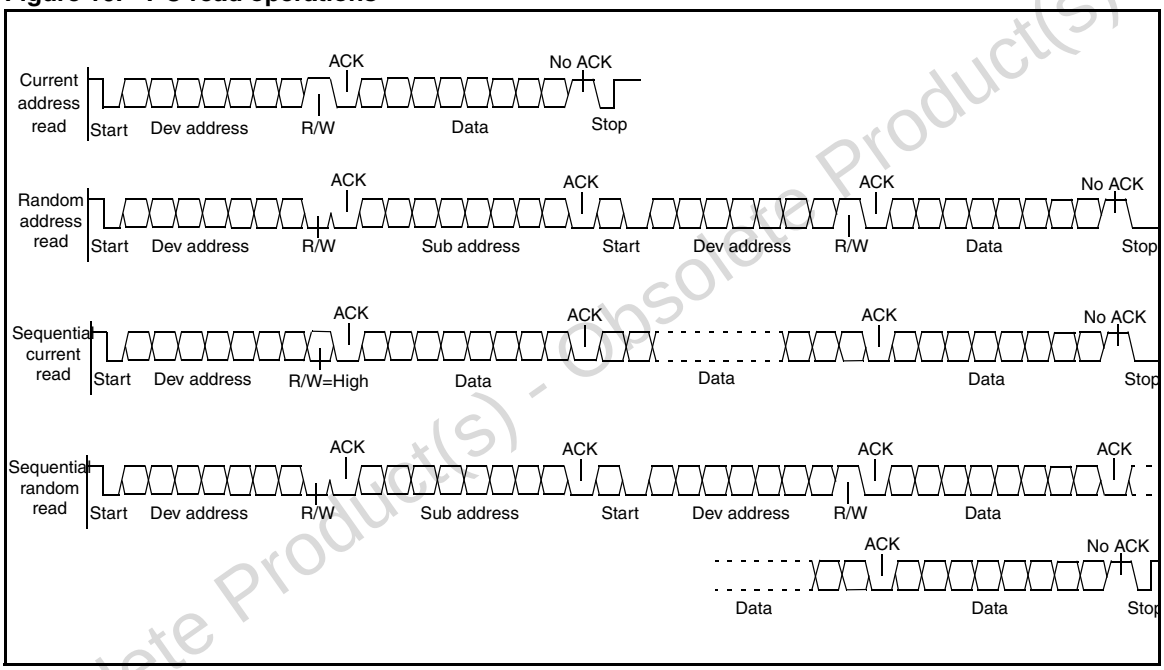


Figure 16. I²C read operations



10 Registers

This section includes register information.

10.1 Summary

Table 20. Register summary

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
0x00	FFXCFG0	MUTE	POW_STBY	SOFT_VOL_ON	BIN_SOFTSTART	TIM_SOFT_VOL[3:0]			
0x01	FFXCFG1	L1_R2	MUTE_ON_INVALID	PWM_MODE[1:0]		PWM_SHIFT[1:0]			
0x02	MVOL	SET_VOL_MASTER[7:0]							
0x03	LVOL	SET_VOL_LEFT[7:0]							
0x04	RVOL	SET_VOL_RIGHT[7:0]							
0x05	TTF0	TIM_TS_FAULT[15:8]							
0x06	TTF1	TIM_TS_FAULT[7:0]							
0x07	TTP0	TIM_TS_POWUP[15:8]							
0x08	TTP1	TIM_TS_POWUP[7:0]							
0x0A	S2PCFG0	BICLK_STRB	LRCLK_LEFT	SHARE_BILR	MSB_FIRST	DATA_FORMAT[2:0]			MASTER_MODE
0x0B	S2PCFG1	PDATA_LENGTH[1:0]		BICLK_OS[1:0]		MAP_L[1:0]		MAP_R[1:0]	
0x0C	P2SCFG0	BICLK_STRB	LRCLK_LEFT	SDATAO_ACT	MSB_FIRST	DATA_FORMAT[2:0]			MASTER_MODE
0x0D	P2SCFG1	PDATA_LENGTH[1:0]		BICLK_OS[1:0]		MAP_L[1:0]		MAP_R[1:0]	
0x14	PLLCFG0	PLL_DIRECT_PROG	FRAC_CTRL	DITHER_DISABLE[1:0]		IDF[3:0]			
0x15	PLLCFG1	FRAC_INPUT[15:8]							
0x16	PLLCFG2	FRAC_INPUT[7:0]							
0x17	PLLCFG3	STRB	STRB_BYPASS	NDIV[5:0]					
0x18	PLLPFE	PLL_BYP_UNL	BICLK2PLL	PLL_PWDN	PFE1A	PFE1B	PFE2A	PFE2B	RESET_FAULT
0x19	PLLST	PLL_UNLOCK	PLL_PWD_STATE	PLL_BYP_STATE					
0x1E	ADCCFG	PGA[2:0]			INSEL	STBY	BYPASS_CALIB	CLKENBL	
0x1F	CKOCFG	CLKOUT_DIS	CLKOUT_SEL[1:0]						
0x20	MISC	OSC_DIS	P2P_FS_RANGE[2:0]			ADC_FS_RANGE[1:0]		P2P_IN_ADC	CORE_CLKENBL
0x21	PADST0	Reserved							
0x22	PADST1	Reserved							
0x23	FFXST						INVALID_INP_FBK	MUTE_INT_FBK	BINSS_FBK
0x28	BISTRUN	Reserved							

Table 20. Register summary (continued)

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
0x29	BISTST0	Reserved							
0x2A	BISTST1	Reserved							
0x2B	BISTST2	Reserved							
0x2D	PWMINT1	PWM_INT[15:8]							
0x2E	PWMINT2	PWM_INT[7:0]							
0x32	POWST	POWER DOWN	POW_ TRISTATE	POW_ FAULT1A	POW_ FAULT1B	POW_ FAULT2A	POW_ FAULT2B		

10.2 General registers

FFXCFG0 FFX configuration register 0

Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
MUTE	POW_STBY	SOFT_VOL_ON	BIN_ SOFTSTART	TIM_SOFT_VOL[3:0]			

Address: 0x00

Type: R/W

Buffer: No

Reset: 0x75

Description:

7 MUTE:
0: default
1: FFX output is zero

6 POW_STBY:
0: FFX bridge is in power-up mode
1: FFX bridge is put in standby mode (default)

5 SOFT_VOL_ON:
0: smooth transition not active
1: smooth transition when changing volume control (default)

4 BIN_SOFTSTART:
Reserved (1: default)

3:0 TIM_SOFT_VOL: volume control time step for any 0.5 dB volume change
Time is $(2^{TIM\_SOFT\_VOL}) * 20.83\ \mu s$
Default is 666.66 µs

FFXCFG1 Configuration register 1

Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
L1_R2	MUTE_ON_ INVALID	PWM_MODE[1:0]		PWM_SHIFT[1:0]			

Address: 0x01

Type: R/W

Buffer: No

Reset: 0xf8

Description:

7 L1_R2: channel mapping:
0: right channel is mapped to output channel 1 and left channel is mapped to output channel 2
1: left channel is mapped to output channel 1 and right channel is mapped to output channel 2 (default)

6 MUTE_ON_ INVALID: mutes PWM outputs if invalid digital data is received:
0: outputs are not muted
1: outputs are muted (default)

5:4 PWM_MODE[1:0]:
00: binary (output B is opposite of output A)
01: binary headphones (output B is 50 % duty cycle)
10: ternary
11: phase shift (default)

3:2 PWM_SHIFT[1:0]:
10: default
PWM period-shift between channels 1 and 2
Value is N * 90^{o}
Default is 180^{o}

1:0 Reserved (00: default)

MVOL Master volume control register

Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
SET_VOL_MASTER[7:0]							

Address: 0x02

Type: R/W

Buffer: No

Reset: 0x00

Description:

7:0 SET_VOL_MASTER[7:0]: master volume control:
From 0 dB to -127.5 dB in 0.5 dB steps

LVOL Left channel volume control register

Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
SET_VOL_LEFT[7:0]							

Address: 0x03

Type: R/W

Buffer: No

Reset: 0x48

Description:

7:0 SET_VOL_LEFT[7:0]: left channel volume control:
0100 1000: default
Left channel volume control (from +36 dB to -91.5 dB in 0.5 dB steps)
Default value corresponds to 0 dB

RVOL Right channel volume control register

Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
SET_VOL_RIGHT[7:0]							

Address: 0x04

Type: R/W

Buffer: No

Reset: 0x48

Description:

7:0 SET_VOL_RIGHT[7:0]: right channel volume control:
0100 1000: default
Right channel volume control (from +36 dB to -91.5 dB in 0.5 dB steps)
Default value corresponds to 0 dB

TTF0 Tri-state time-after-fault register 0

Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
TIM_TS_FAULT[15:8]							

Address: 0x05

Type: R/W

Buffer: No

Reset: 0x00

Description:

7:0 MSBs of TIM_TS_FAULT[15:8]:
See *TTF1 on page 40*.

TTF1 Tri-state time-after-fault register 1

Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
TIM_TS_FAULT(7:0)							

Address: 0x06

Type: R/W

Buffer: No

Reset: 0x02

Description:

7:0 LSBs of TIM_TS_FAULT[7:0]: time in which power is held in tri-state mode after a fault signal:
Time is TIM_TS_FAULT * 83.33 µs.
Default value corresponds to 166.66 µs tri-state time after fault

TTP0 Tri-state time-after-power-up register 0

Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
TIM_TS_POWUP[15:8]							

Address: 0x07

Type: R/W

Buffer: No

Reset: 0x00

Description:

7:0 MSBs of TIM_TS_POWUP[15:8]:
See register *TTP1*.

TTP1 Tri-state time-after-power-up register 1

Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
TIM_TS_POWUP[7:0]							

Address: 0x08

Type: R/W

Buffer: No

Reset: 0x02

Description:

7:0 LSBs of TIM_TS_POWUP[7:0]: time in which power is held in tri-state mode after a power-up signal:
Time is TIM_TS_POWUP * 83.33 µs
Default value corresponds to 166.66 µs tri-state time after power-up

S2PCFG0 Serial-to-parallel audio interface configuration register 0

Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
BICLK_STRB	LRCLK_LEFT	SHARE_BILR	MSB_FIRST	DATA_FORMAT[2:0]			MASTER_ MODE

Address: 0x0A

Type: R/W

Buffer: No

Reset: 0xD2

Description:

7 BICLK_STRB:
0: bit clock strobe edge is falling edge, bit clock active edge is rising edge
1: bit clock strobe edge is rising edge, bit clock active edge is falling edge (default)

6 LRCLK_LEFT:
0: left/right clock is low for left channel, high for right channel
1: left/right clock is high for left channel, low for right channel (default)

5 SHARE_BILR:
0: default
1: left/right clock and bit clock are shared between serial-parallel interface and parallel-to-serial interface, BICLKI and LRCLKI are used

4 MSB_FIRST:
0: LSB first
1: MSB first (default)

3:1 DATA_FORMAT[2:0]: serial interface protocol format:
000: left Justified
001: I^2S (default)
010: right justified
100: PCM no delay
101: PCM delay
111: DSP
001: default

0 MASTER_MODE:
0: default
1: serial interface is in master mode

S2PCFG1 Serial-to-parallel audio interface configuration register 1

Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
PDATA_LENGTH[1:0]		BICLK_OS[1:0]		MAP_L[1:0]		MAP_R[1:0]	

Address: 0x0B

Type: R/W

Buffer: No

Reset: 0x91

Description:

7:6 PDATA_LENGTH[1:0]: serial-to-parallel interface data length:
10: default
Length is (N+1) * 8 bit
Default is 24 bit

5:4 BICLK_OS[1:0]: bit clock oversampling:
01: default
Value is (N+1) * 32 fs (where fs = sampling frequency)
Default is 64 fs

3:2 MAP_L[1:0]: left data-mapping slot:
00: default
Value is nth slot
Default is slot0

1:0 MAP_R[1:0]: right data-mapping slot:
01: default
Value is nth slot
Default is slot

P2SCFG0 Parallel-to-serial audio interface configuration register 0

Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
BICLK_ STRB	LRCLK_LEFT	SDATAO_ACT	MSB_FIRST	DATA_FORMAT[2:0]			MASTER_ MODE

Address: 0x0C

Type: R/W

Buffer: No

Reset: 0xD3

Description:

7 BICLK_STRB: defines the bit clock edges:
0: strobe is falling edge, active edge is rising
1: strobe is rising edge, active edge is falling (default)

6 LRCLK_LEFT: defines the channel for the LR clock:
0: clock is low for left channel, high for right channel
1: clock is high for left channel, low for right channel (default)

5 SDATAO_ ACT: sets the behavior of pin SDATAO:
0: output is tri-stated when no data is sent (default)
1: output is never in tri-state (it is 0 when no data is sent)

4 MSB_FIRST: data alignment in the protocol for SDATAI and SDATAO:
0: LSB is the first bit
1: MSB is the first bit (default)

3:1 DATA_FORMAT[2:0]: serial interface protocol format:
000: left justified
001: I^2S (default)
010: right justified
100: PCM no delay
101: PCM delay
111: DSP

0 MASTER_ MODE: selects serial interface master/slave mode:
0: slave
1: master (default)

P2SCFG1 Parallel-to-serial audio interface configuration register 1

Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
PDATA_LENGTH[1:0]		BICLK_OS[1:0]		MAP_L[1:0]		MAP_R[1:0]	

Address: 0x0D

Type: R/W

Buffer: No

Reset: 0x91

Description:

7:6 PDATA_LENGTH[1:0]: serial-to-parallel interface data length:
10: default
Length is (PDATA_LENGTH+1) * 8 bit
Default is 24 bits

5:4 BICLK_OS[1:0]: bit clock oversampling:
01: default
Value is (BICLK_OS+1) * 32 fs
Default is 64 fs

3:2 MAP_L[1:0]: left data-mapping slot:
00: default
Value is nth slot
Default is slot0

1:0 MAP_R[1:0]: right channel data-mapping slot:
01: default
Value is nth slot
Default is slot1

PLLCFG0 PLL configuration register 0

Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
PLL_DIRECT_PROG	FRAC_CTRL	DITHER_DISABLE[1:0]		IDF[3:0]			

Address: 0x14

Type: R/W

Buffer: No

Reset: 0x00

Description:

7 PLL_DIRECT_PROG: PLL programming:
0: default
1: PLL is programmed according to the PLLCFG register settings

6 FRAC_CTRL:
0: default
1: PLL fractional-frequency synthesis is enabled

5:4 DITHER_DISABLE[1:0]:
00: default
MSB = 1: disables rectangular PDF dither input to SDM
LSB = 1: disables triangular PDF dither input to SDM

3:0 IDF[3:0]: PLL input division factor:
0000: IDF = 1 (default)
0001: IDF = 1
0010: IDF = 2
…
1111: IDF = 15

PLLCFG1 PLL configuration register 1

Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
FRAC_INPUT[15:8]							

Address: 0x15

Type: R/W

Buffer: No

Reset: 0x00

Description:

7:0 FRAC_INPUT[15:8]: 16 bits are used to set the fractional part of PLL multiplication factor:
0000 0000: default

PLLCFG2 PLL configuration register 2

Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
FRAC_INPUT[7:0]							

Address: 0x16

Type: R/W

Buffer: No

Reset: 0x00

Description:

7:0 FRAC_INPUT[7:0]: 16 bits are used to set the fractional part of PLL multiplication factor:
0000 0000: default

PLLCFG3 PLL configuration register 3

Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
STRB	STRB_BYPASS	NDIV[5:0]					

Address: 0x17

Type: R/W

Buffer: No

Reset: 0x00

Description:

7 STRB: asynchronous strobe input to the fractional controller:
0: default

6 STRB_BYPASS: standby bypass:
0: STRB signal is not bypassed (default)
1: STRB signal is bypassed

5:0 NDIV[5:0]: PLL multiplication factor (integral part) named as loop division factor:
0000 XX: LDF = NA
0001 00: LDF = NA
0001 01: LDF = 5
...
1101 11: LDF = 55
111X XX: LDF = NA
0000 00: default

PLLPFE PLL/POP-free configuration register

Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
PLL_BYP_UNL	BICLK2PLL	PLL_PWDN	PFE1A	PFE1B	PFE2A	PFE2B	RESET_FAULT

Address: 0x18

Type: R/W

Buffer: No

Reset: 0x00

Description:

7 PLL_BYP_UNL: PLL bypass:
0: PLL is not bypassed (default)
1: PLL is bypassed when not locked

6 BICLK2PLL:
0: default
1: BICLKI is input to PLL

5 PLL_PWDN:
0: default
1: PLL is put in power-down mode

4 PFE1A:
0: default
1: POP-free resistances are connected to output 1A

3 PFE1B:
0: default
1: POP-free resistances are connected to output 1B

2 PFE2A:
0: default
1: POP-free resistances are connected to output 2A

1 PFE2B:
0: default
1: POP-free resistances are connected to output 2B

0 RESET_FAULT:
0: default
1: fault signal in the i2c register POWST is reset

PLLST PLL status register (RO)

Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
PLL_UNLOCK	PLL_PWD_ STATE	PLL_BYP_ STATE					

Address: 0x19

Type: RO

Buffer: No

Reset: Undefined

Description:

7 PLL_UNLOCK: PLL unlock state:
0: PLL is not in unlock state
1: PLL is in unlock state

6 PLL_PWD_ STATE: PLL power-down state:
0: PLL is not in power-down state
1: PLL is in power-down state

5 PLL_BYP_STATE: PLL bypass state:
0: PLL is not in bypass state
1: PLL is in bypass state

4:0 Reserved

ADCCFG ADC configuration register

Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
PGA[2:0]			INSEL	STBY	BYPASS_CALIB	CLKENBL	

Address: 0x1E

Type: RO

Buffer: No

Reset: Undefined

Description:

7:5 PGA[2:0]: gain selection bits for the ADC programmable gain amplifier:
000: default
Values are from 0 to 42 dB in 6 dB steps

4 INSEL:
0: line input selected (default)
1: microphone input selected (it must be applied to INL line)

3 STBY: ADC standby mode:
0: ADC in power-up mode (default)
1: ADC in standby mode

2 BYPASS_CALIB:
0: ADC DC-removal block not bypassed (default)
1: ADC DC-removal block bypassed

1 CLKENBL: Clock enable:
0: system clock not enabled
1: system clock available at ADC input (default)

0 Reserved

CKOCFG Clock-out configuration register

Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
CLKOUT_DIS	CLKOUT_SEL[1:]]						

Address: 0x1F

Type: R/W

Buffer: No

Reset: Undefined

Description:

7 CLKOUT_DIS: CLKOUT PAD disabled
0: default
1: enabled

6:5 CLKOUT_SEL[1:0]:
00: default
The CLKOUT output frequency is the PLL output frequency divided by 2^{CLKOUT_SEL}.

4:0 Reserved

MISC Miscellaneous configuration register

Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
OSC_DIS	P2P_FS_RANGE[2:0]			ADC_FS_RANGE[1:0]		P2P_IN_ADC	CORE_ CLKENBL

Address: 0x20

Type: R/W

Buffer: No

Reset: 0x21

Description:

7 OSC_DIS: enable/disable crystal oscillator:
0: default
1: disabled

6:4 P2P_FS_RANGE[2:0]: FFX audio frequency range:
000: very low (fs = 8 to 12 kHz) (default)
001: low (fs = 16 to 24 kHz) (default)
010: normal (fs = 32 to 48 kHz)
011: high (fs = 64 to 96 kHz)
1X: very high (fs = 128 to 192 kHz)

3:2 ADC_FS_RANGE[2:0]: ADC audio frequency range:
00: normal (fs = 32 to 48 kHz)
00: low (fs = 16 to 24 kHz)
1X: very low (fs = 8 to 12 kHz)
00: default

1 P2P_IN_ADC: FFX input:
0: FFX input is from serial-to-parallel audio interface (default)
1: FFX input is from ADC

0 CORE_CLKENBL: availability of system clock:
0: FFX system clock disabled
1: FFX system clock enabled (default)

FFXST FFX status register

Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
					INVALID_INP_FBK	MUTE_INT_FBK	

Address: 0x23

Type: RO

Buffer: No

Reset: Undefined

Description:

7:3 Reserved

2 INVALID_INP_FBK: invalid input status:
1: invalid input sent to FFX

1 MUTE_INT_FBK: FFX mute status
1: FFX is in mute state

0 Reserved

PWMINT1 PWM driver configuration register 1

Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
PWM_INT1[7:0]							

Address: 0x2D

Type: R/W

Buffer: No

Reset: 0x00

Description:

7:0 PWM_INT1[7:0]: see *Section 7: Driver configuration on page 26*:
0000 0000: default

PWMINT2 PWM driver configuration register 2

Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
PWM_INT1[7:0]							

Address: 0x2E

Type: R/W

Buffer: No

Reset: 0x00

Description:

7:0 PWM_INT1[7:0]: see *Section 7: Driver configuration on page 26*:
0000 0000: default

POWST Power bridge status register

Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
POW_ POWERDOWN	POW_ TRISTATE	POW_FAULT1A	POW_FAULT1B	POW_FAULT2A	POW_FAULT2B		

Address: 0x32

Type: RO

Buffer: No

Reset: Undefined

Description:

7 POW_POWERDOWN: power-down bridge:
0: not in power-down state
1: power-down state

6 POW_TRISTATE:
1: power bridge is in tri-state

5 POW_FAULT1A:
1: power bridge 1A is in fault state

4 POW_FAULT1B:
1: power bridge 1B is in fault state

3 POW_FAULT2A:
1: power bridge 2A is in fault state

2 POW_FAULT2B:
1: power bridge 2B is in fault state

1:0 Reserved

11 Package information

This section includes packaging information for the following packages:

- TFBGA48
- VFQFPN52

In order to meet environmental requirements, ST offers these devices in ECOPACK® packages. These package have a lead-free second level interconnect. The category of second level interconnect is marked on the package and on the inner box label, in compliance with JEDEC Standard JESD97. The maximum ratings related to soldering conditions are also marked on the inner box label. ECOPACK is an ST trademark. ECOPACK specifications are available at: www.st.com.

11.1 Package TFBGA48

Figure 17. Mechanical data (TFBGA48)

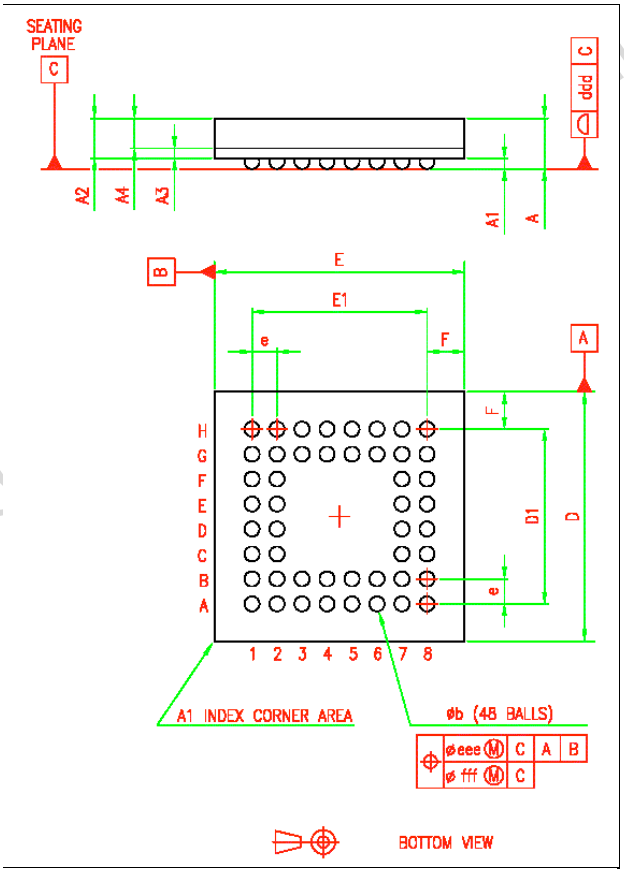


Table 21 gives the package dimensions.

Table 21. Package dimensions (TFBGA48)

	Databook mm		
Reference	**Min**	**Typical**	**Max**
A			1.20
A1	0.15		
A2		0.785	
A3		0.20	
A4			0.60
b	0.25	0.30	0.35
D	4.85	5.00	5.15
D1		3.50	
E	4.85	5.00	5.15
E1		3.50	
e		0.50	
F		0.75	
ddd			0.08
eee			0.15
fff			0.05

11.2 Package VFQFPN52

Figure 18. Mechanical data (VFQFPN52)

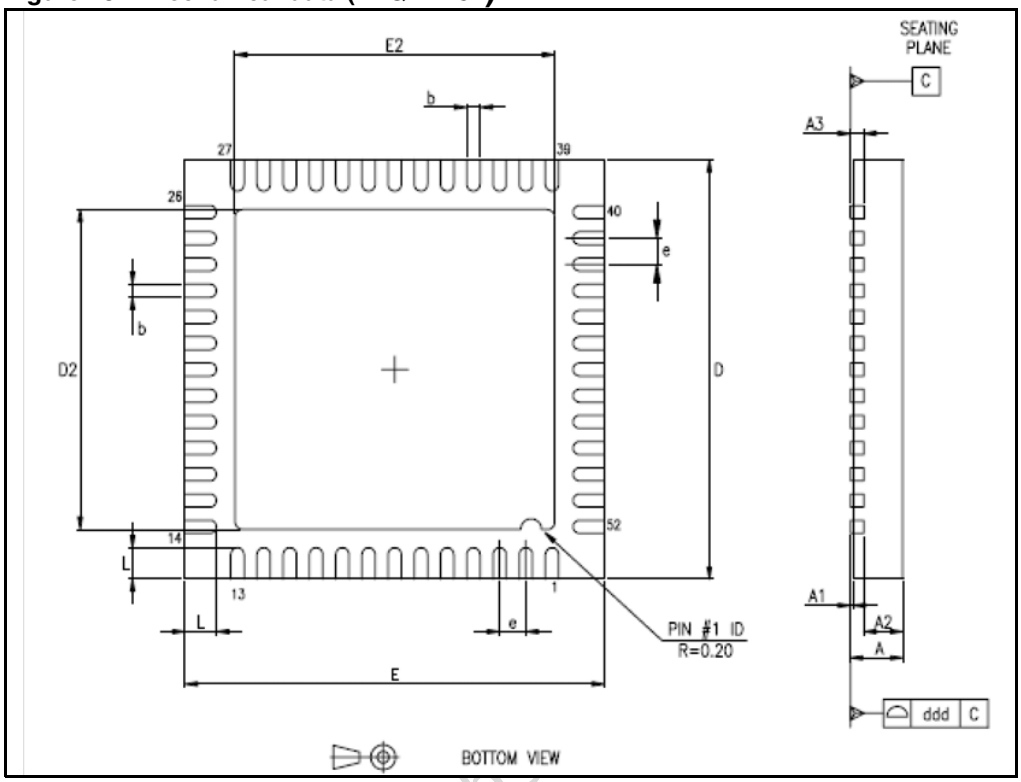


Table 22 gives the package dimensions.

Table 22. Package dimensions (VFQFPN52)

	Databook mm		
Reference	**Min**	**Typical**	**Max**
A	0.800	0.900	1.000
A1		0.020	0.050
A2		0.650	1.000
A3		0.250	
b	0.180	0.230	0.300
D	7.875	8.000	8.125
D2	2.750	5.700	6.250
E	7.875	8.000	8.125
E2	2.750	5.700	6.250
e	0.450	0.500	0.550
L	0.350	0.550	0.750
ddd			0.080

12 Revision history

Table 23. Document revision history

Date	Revision	Changes
25-Jan-2007	1	Initial release

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